

## Special Issue

# Silicon Photonics Packaging: Connecting Photonic Integrated Circuits with the Outside World

### Message from the Guest Editors

After decades of academic research, silicon photonic integrated circuits (PICs) are widely deployed in industry nowadays. Several foundries offer Si photonics multi-project wafer (MPW) runs, which makes the technology accessible not only to corporations, but also to small research labs and early stage startups. After wafer- and die-scale lab testing, PICs require packaging into a durable module that will connect them to the outside world and protect them from harsh environments. In the next step of Si PIC productization, the packaging technology should ensure reliable operation, high PIC performance, and low cost. Thus, there will be significant momentum in academia and industry for developing and standardizing robust packaging solutions for fast Si PIC introduction. This Special Issue aims to highlight the current progress and recent state-of-the-art in Si PIC packaging. Research areas may include (but are not limited to) the following: advanced fiber-to-PIC attachment (edge, grating, evanescent coupling), wafer-scale packaging, laser integration, micro-optics assembly, photonic MEMS packaging, electronic-photonic co-integration, and assembly thermal management.

### Guest Editors

Dr. Aleksandrs Marinins

Advanced Packaging Engineer at Nokia of America Corporation,  
Sunnyvale, CA, USA

Dr. Nouman Zia

Faculty of Engineering and Natural Sciences, Tampere University,  
Tampere, Finland

### Deadline for manuscript submissions

closed (15 June 2024)



## Photonics

an Open Access Journal  
by MDPI

Impact Factor 1.9  
CiteScore 3.5



[mdpi.com/si/147454](https://mdpi.com/si/147454)

*Photonics*  
Editorial Office  
MDPI, Grosspeteranlage 5  
4052 Basel, Switzerland  
Tel: +41 61 683 77 34  
[photonics@mdpi.com](mailto:photonics@mdpi.com)

[mdpi.com/journal/  
photonics](https://mdpi.com/journal/photonics)





# Photonics

---

an Open Access Journal  
by MDPI

---

Impact Factor 1.9  
CiteScore 3.5



[mdpi.com/journal/  
photonics](https://mdpi.com/journal/photonics)



## About the Journal

### Message from the Editor-in-Chief

You are invited to contribute a research article or a comprehensive review for consideration and publication in *Photonics* (ISSN 2304-6732). *Photonics* is an online open access journal covering both the fundamental and applications of optics and photonics. *Photonics* strives to provide an avenue to allow authors to disseminate their scientific findings—both theoretical/ simulations and experimental works—in highly accessible peer-reviewed journal publications. The manuscript in *Photonics* will be handled with quick turnaround production processing time. We welcome authors to submit their manuscripts for publications in *Photonics*. Our goal in *Photonics* is to enable fast dissemination of high impact works to the scientific community.

---

### Editor-in-Chief

Prof. Dr. Nelson Tansu

School of Electrical and Electronic Engineering (EEE), The University of Adelaide, Adelaide, SA 5005, Australia

---

### Author Benefits

#### High Visibility:

indexed within Scopus, SCIE (Web of Science), Inspec, Ei Compendex, CAPlus / SciFinder, and other databases.

#### Journal Rank:

CiteScore - Q2 (Instrumentation)

#### Rapid Publication:

manuscripts are peer-reviewed and a first decision is provided to authors approximately 14.8 days after submission; acceptance to publication is undertaken in 1.9 days (median values for papers published in this journal in the first half of 2025).